

(11) Publication number:

11186423

Generated Document.

PATENT ABSTRACTS OF JAPAN

(21) Application number: **09353173**

(51) Intl. Cl.: **H01L 23/02** C04B 37/02 H01L 23/04

(22) Application date: 22.12.97

(30) Priority:

(43) Date of application

publication:

09.07.99

(84) Designated contracting

states:

(71) Applicant: SUMITOMO METAL MINING CO

(72) Inventor: MORI NOBUMOTO

(74) Representative:

(54) HERMETIC SEAL COVER AND ITS MANUFACTURE

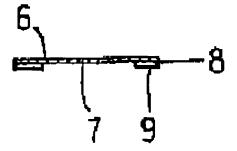
(57) Abstract:

PROBLEM TO BE SOLVED: To implement a highly reliable hermetic seal by providing a brazing filler metal layer on a gold-planting layer on a member of a desired shape, a metal layer which has a predetermined thickness and is hard to oxidize on the brazing filler metal layer, and eliminating an oxide form the interface between the brazing filler metal layer.

SOLUTION: A seal cover 6 is manufactured by forming a gold-plating layer 7 on the surface of a ceramic member by barrel planting, and then by forming a gold-tin alloy prazing filler metal layer 8 while ponding the alloy by thermocompression in desired positions on one surface of the layer 7. Then, an oxide film on the gold-tin prazing filler metal surface is temoved in a pre-plating process step, and a gold-plating film 9 whose thickness range from 0.01 to 1.0 μm is formed on the gold-tin brazing

filler metal surface using a commercially available gold plating solution. The seal cover 6 for nemetically sealing an object has a metal-plating film that is hard to oxidize, i.e., the film 9 formed on the surface from which the oxide film of the brazing filler metal member has been removed. Therefore, no voids are produced when the object is nermetically sealed, and thus the object can be sealed reliably.

COPYRIGHT: (C)1999,JPO





The Delphion Integrated View

Other Views: INPADOC

Title:

JP11186423A2: HERMETIC SEAL COVER AND ITS MANUFACTURE

Want to see a more descriptive title highlighting what's new about this invention?

Country:

JP Japan

Kind:

d: 🖊

Inventor(s):

MORI NOBUMOTO

Applicant/Assignee:

Inquire Regarding
Licensing

SUMITOMO METAL MINING CO LTD

News, Profiles, Stocks and More about this company

Issued/Filed Dates:

July 9, 1999 / Dec. 22, 1997

Application Number:

JP1997000353173

IPC Class:

H01L 23/02; C04B 37/02; H01L 23/04;

Priority Number(s):

Dec. 22, 1997 JP19971997353173

Abstract:

Problem to be solved: To implement a highly reliable hermetic seal by providing a brazing filler metal layer on a gold-planting layer on a member of a desired shape, a metal layer which has a predetermined thickness and is hard to oxidize on the brazing filler metal layer, and eliminating an oxide form the interface between the brazing filler metal layer and the metal layer.



Solution: A seal cover 6 is manufactured by forming a gold-plating layer 7 on the surface of a ceramic member by barrel planting, and then by forming a gold-tin alloy brazing filler metal layer 8 while bonding the alloy by thermocompression in desired positions on one surface of the layer 7. Then, an oxide film on the gold-tin brazing filler metal surface is removed in a pre- plating process step, and a gold-plating film 9 whose thickness range from 0.01 to 1.0 µm is formed on the gold-tin brazing filler metal surface using a commercially available gold plating solution. The seal cover 6 for hemetically sealing an object has a metal-plating film that is hard to oxidize, i.e., the film 9 formed on the surface from which the oxide film of the brazing filler metal member has been removed. Therefore, no voids are produced when the object is hermetically sealed, and thus the object can be sealed reliably.

COPYRIGHT: (C)1999,JPO

See a clear and precise summary of the whole patent, in understandable terms.

Family:

Show known family members

Other Abstract Info:

CHEMABS 131(07)096016G CHEMABS 131(07)096016G DERABS

C1999-450231 DERABS C1999-450231

Foreign References:

No patents reference this one

eh c e





Nominate this for the Gallery...

<u>Subscribe</u> | <u>Privacy Policy</u> | <u>Terms & Conditions</u> | <u>FAQ</u> | <u>Site Map</u> | <u>Help</u> | <u>Contact Us</u> © 1997 - 2002 Delphion Inc.